

## Description

The AP3129 is a highly integrated multi-mode peak current controller, which specially provides high efficiency at light load for IoT application. Meanwhile, the AP3129 features a proprietary audible noise elimination technology to ease the acoustic noises from electronic and magnetic components.

The AP3129 is a multi-mode controller, which changes operating mode according to load conditions. Under heavy-load condition, the device operates in CCM (continuous-conduction mode) with a fixed switching frequency of 65kHz, which is helpful to system design with small transformer size. When the loading is decreasing, it enters QR (Quasi Resonant) or Green mode with valley switching for the higher power conversion efficiency. At light load or no load, the IC will operate with its proprietary burst mode to minimize power consumption with the minimum switching frequency (about 22kHz).

The controller architecture is designed to authorize a transient peak power excursion for peak load. It means the frequency can be increased from 65kHz to 130kHz until the peak event disappears.

In addition, piecewise linear line compensation ensures accurate constant output power limit over an entire line voltage range.

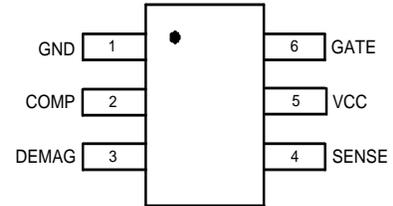
## Features

- Multiple Operation Modes
  - 130kHz Maximum Frequency for Peak Load
  - 65kHz Fixed-Frequency CCM Operation for Full Load
  - 80kHz Maximum Clamping Frequency for QR Mode
  - Valley Switching Operation in Green Mode
  - Burst Mode Control for Light Load
- High Efficiency at Light Load (> 90% Efficiency at 10% Load)
- Proprietary Audible Noise Elimination Technology
- Soft Start During Startup Process
- Internal Slope Compensation
- Frequency Dithering for Reducing EMI
- VCC Maintain Mode
- Low No-Load Consumption
- Comprehensive System Protection Features
  - Secondary Winding Short Protection
  - VCC Overvoltage Protection (VOVP)
  - Line Overvoltage Protection (LOVP)
  - Overload Protection (OLP)
  - Cycle-by-Cycle Overcurrent Protection
  - Pin-Fault Protection
  - Brown-In/Out Protection (BNI/BNO)
  - Secondary Side OVP (SOVP) and UVP (SUVP)
  - Internal OTP
- SOT26 (Type CJ) is Available
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

## Pin Assignments

(Top View)



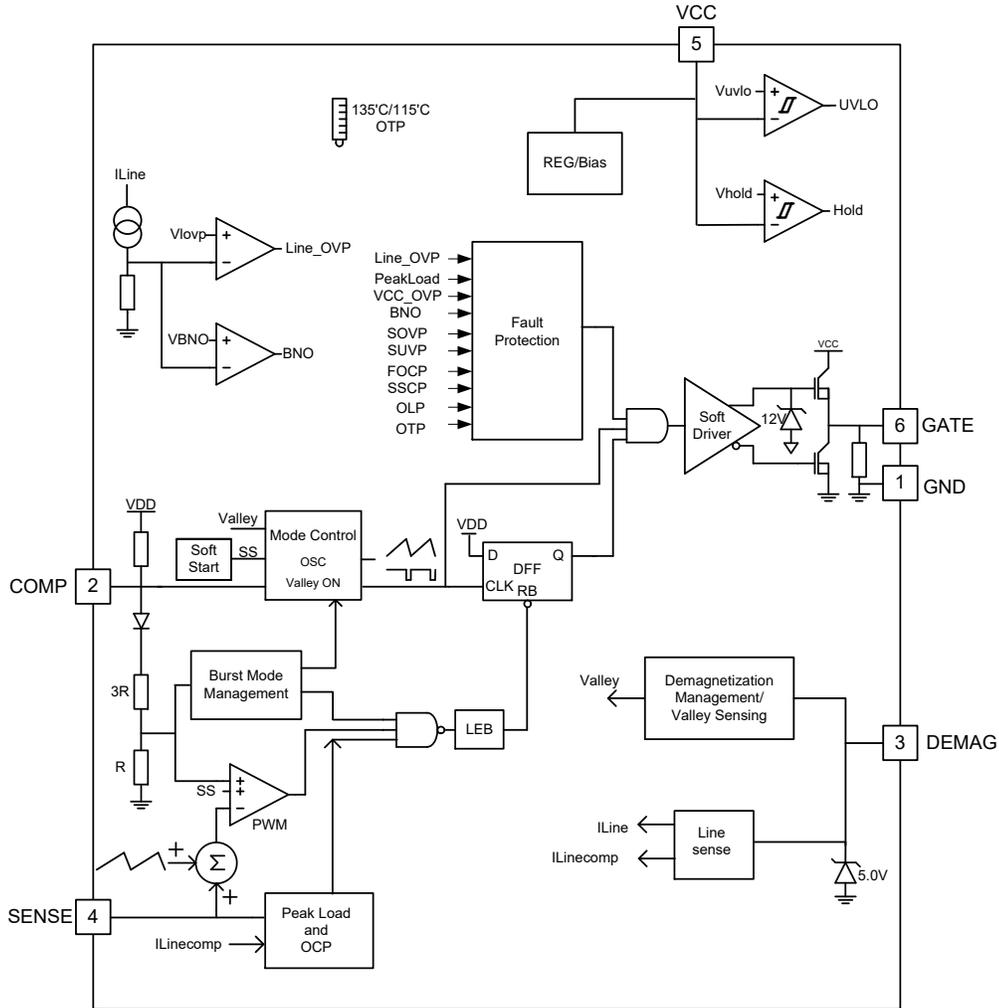
SOT26 (Type CJ)

## Applications

- IoT (Internet of Thing) offline power
- Home appliances: smart speakers, AC fans, rice cookers, shavers, milk machines
- TV/Monitor standby power
- AC/DC adapters or quick chargers



**Functional Block Diagram**



**Absolute Maximum Ratings** (Note 4)

Symbol	Parameter	Rating	Unit
VCC	Power Supply Voltage	32	V
VCOMP, VSENSE, VDEMAG	COMP, SENSE, DEMAG Pins Input Voltage (Note 5)	-0.3 to 7	V
VGATE	Gate Pin Voltage (Note 5)	-0.3 to 16	V
$\theta_{JA}$	Thermal Resistance (Junction to Ambient) (Note 6)	149	°C/W
$\theta_{JC}$	Thermal Resistance (Junction to Case) (Note 6)	75	°C/W
P <sub>D</sub>	Power Dissipation at T <sub>A</sub> < +25°C	500	mW
T <sub>J</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
ESD	Human Body Model	2,000	V
	Charge Device Model	800	V

Notes: 4. Stresses greater than those listed under *Absolute Maximum Ratings* can cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to *Absolute Maximum Ratings* for extended periods can affect device reliability.  
 5. If -0.3V to -0.5V negative voltage is applied to DEMAG/SENSE/GATE pin, the period of negative pulse is lower than 0.4µs.  
 6. Test condition: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch<sup>2</sup> cooling area.

## Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	9	26	V
T <sub>A</sub>	Ambient Temperature	-40	+85	°C

## Electrical Characteristics (@ T<sub>A</sub> = -40°C to +85°C, V<sub>CC</sub> = 18V, unless otherwise specified.)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Supply Voltage (VCC Pin)</b>						
V <sub>CC_OVP</sub>	VCC OVP Threshold Voltage	—	26.5	28	29.5	V
V <sub>CC_ON</sub>	VCC On Threshold Voltage	—	16.5	18	19.5	V
V <sub>CC_UVLO</sub>	VCC UVLO Threshold Voltage	—	5.8	6.3	6.8	V
V <sub>CC_ET</sub>	VCC Holdup Mode Entry Point	—	6.5	7.3	8.0	V
V <sub>CC_EX</sub>	VCC Holdup Mode Exit Point	—	—	V <sub>CC_ET</sub> +0.8	—	V
I <sub>CC_ST</sub>	Startup Current	V <sub>CC</sub> < V <sub>CC_ON</sub>	—	1	5	μA
I <sub>CC_OP</sub>	Operating Current	V <sub>COMP</sub> = 0V, I <sub>DEMAG</sub> = 0mA	300	376	425	μA
		V <sub>COMP</sub> = 1.2V, V <sub>CC</sub> = 16V	0.75	0.9	1.15	mA
<b>GATE Section (GATE Pin)</b>						
V <sub>GATE_H</sub>	GATE High Voltage	I <sub>SOURCE</sub> = 20mA, V <sub>CC</sub> = 16V	10	11.5	13.5	V
V <sub>GATE_L</sub>	GATE Low Voltage	I <sub>SINK</sub> = 20mA, V <sub>CC</sub> = 16V	—	0.06	0.20	V
t <sub>GATE-RISE</sub>	Rising Time	C <sub>L</sub> = 1nF	—	350	—	ns
t <sub>GATE-FALL</sub>	Falling Time	C <sub>L</sub> = 1nF	—	50	—	ns
<b>Current Sense Section (SENSE Pin)</b>						
V <sub>TH_OCP1</sub>	Threshold of OCP1 at Low Line	—	0.5	0.525	0.55	V
R <sub>ocp1</sub>	Rocp at Low Line	I <sub>dem</sub> = 500μA	31	36	41	kΩ
V <sub>TH_OCP2</sub>	Threshold of OCP2 at Low Line	—	0.8	0.825	0.85	V
V <sub>SOCP</sub>	Threshold Voltage of Secondary Rectifier Short Protection	—	1.2	1.25	1.3	V
R <sub>ocp2</sub>	Rocp at Low Line	—	36	41	46	kΩ
V <sub>TH-SSCP</sub>	SSCP Voltage	—	30	50	70	mV
t <sub>LEB</sub>	Leading Edge Blanking Time	—	120	240	370	ns
t <sub>PD</sub>	Internal Propagation Delay Time	—	—	80	—	ns
t <sub>D_OCP1</sub>	Over-Power Protection Debounce Time	(Note 7)	40	60	80	ms
t <sub>D_OCP2</sub>	Peak Load Protection Debounce Time	(Note 7)	10	17	25	ms
<b>Feedback Section (COMP Pin)</b>						
V <sub>COMP_OP</sub>	Open-Loop Voltage	COMP Pin Open-Circuited	4.0	4.5	—	V
V <sub>COMP_PK</sub>	Over Peak Load Protection	—	3.6	3.9	4.25	V
R <sub>COMP</sub>	Internal Pullup Resistor	—	22	27	31	kΩ
K <sub>COMP-SENSE</sub>	The Ratio of V <sub>COMP</sub> to V <sub>SENSE</sub>	—	2.7	3.2	3.7	V/V
V <sub>FB-PEAK-START</sub>	Start of Peak Frequency Rising	Low Line (Note 8)	—	3.45	—	V
		High Line (Note 8)	—	2.45	—	V
V <sub>FB-PEAK-END</sub>	End of Peak Frequency Rising	(Note 8)	—	V <sub>FB-PEAK-START</sub> +0.2	—	V
V <sub>FOLD_EN</sub>	Frequency Foldback Enter Voltage	Low Line	—	2.05	—	V
		High Line (Note 8)	—	1.925	—	V
V <sub>FOLD_EX</sub>	Frequency Foldback Exit Voltage	(Note 8)	—	V <sub>FOLD_EN</sub> -0.35	—	V
V <sub>BURST_ENTRY</sub>	Burst Mode Entry Voltage	Low Line	1.40	1.50	1.60	V
		High Line	1.37	1.47	1.57	V
V <sub>BURST_HYS</sub>	Burst Mode Hysteresis Voltage	—	—	0.030	—	V

Notes: 7. Data measured in IC test mode.  
8. Guaranteed by design.

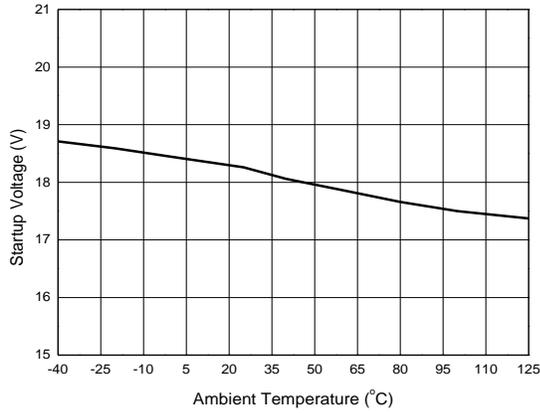
**Electrical Characteristics** (@  $T_A = -40$  to  $+85^\circ\text{C}$ ,  $V_{CC} = 18\text{V}$ , unless otherwise specified.) (continued)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Oscillator Section</b>						
f <sub>SW_PL_MAX</sub>	Maximum Switching Frequency in Peak Load Mode	—	120	130	140	kHz
f <sub>SW_MIN</sub>	Minimum Switching Frequency	—	20	22.5	25	kHz
f <sub>SW_CCM</sub>	Frequency of CCM	High Line	60	65	70	kHz
		Low Line	60	65	70	
D <sub>MAX</sub>	Maximum Duty for Peak Load	—	75	79	83	%
t <sub>MAX_ON</sub>	Maximum t <sub>ON</sub> for Valley-on Switching Mode	—	11	13.5	16	μs
<b>DEMAG Section (DEMAG Pin)</b>						
t <sub>BLK_DEMAG</sub>	Blanking Time	(Note 8)	—	1.4	—	μs
V <sub>TH_OVP</sub>	V <sub>OUT</sub> OVP Threshold Voltage	—	2.7	2.8	2.9	V
V <sub>TH_UVP</sub>	V <sub>OUT</sub> UVP Threshold Voltage	—	0.4	0.5	0.6	V
t <sub>d_UVP</sub>	Blanking Time of V <sub>OUT_UVP</sub>	—	15	25	35	ms
V <sub>ZCD_DEMAG</sub>	Zero Current Detection Threshold Voltage	(Note 7)	—	35	—	mV
t <sub>OUT</sub>	Timeout After Last Zero Current Detection	Correlation with t <sub>BLK_DEMAG</sub> (Note 8)	—	5	—	μs
V <sub>CPL-L</sub>	Low Level for Clamping Voltage	I <sub>DEMAG</sub> = -200μA	-120	-50	—	mV
V <sub>CPL-H</sub>	High Level for Clamping Voltage	I <sub>DEMAG</sub> = 1mA	4.5	5	—	V
I <sub>DEMAG_BNI</sub>	Brown-In Protection Threshold Current	Correlation with I <sub>DEMAG_BNO</sub> (Note 8)	—	-120	—	μA
I <sub>DEMAG_BNO</sub>	Brown-Out Protection Threshold Current	—	-120	-110	-100	μA
t <sub>d_BNO</sub>	Debounce Time of Brown Out	(Note 8)	—	60	—	ms
I <sub>DEMAG_HLSW</sub>	High/Low Line Switching Threshold Current	—	225	-255	285	μA
I <sub>DEMAG_OVP</sub>	Bulk OVP Protection Threshold Current	—	-770	-690	-610	μA
t <sub>d_BulkOVP</sub>	Delay Time of Bulk OVP	(Note 8)	—	3.0	—	s
<b>Internal OTP Section</b>						
OTP	OTP Enter	(Note 8)	—	+135	—	°C
	OTP Exit	(Note 8)	—	+115	—	°C

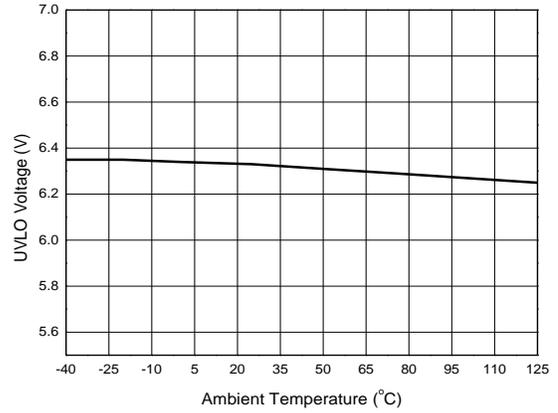
Notes: 7. Data measured in IC test mode.  
8. Guaranteed by design.

**Performance Characteristics**

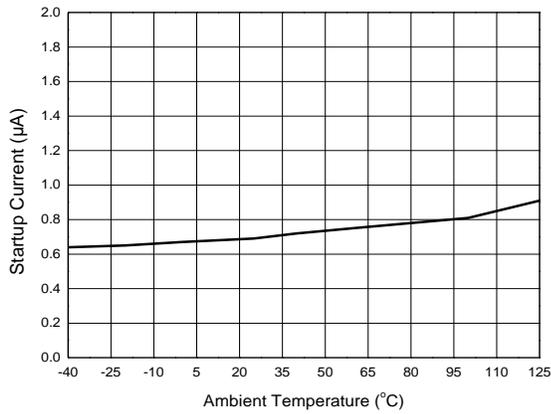
**V<sub>CC\_ON</sub> Threshold vs. Ambient Temperature**



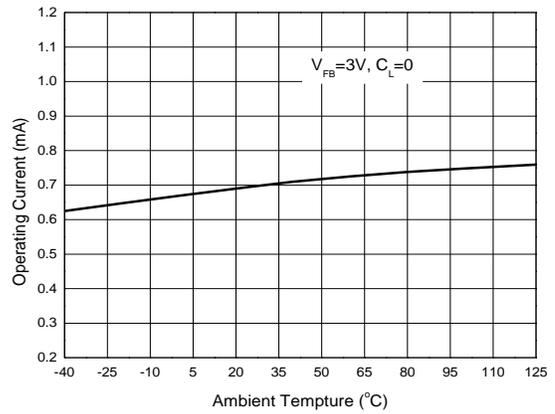
**V<sub>CC\_UVLO</sub> Threshold vs. Ambient Temperature**



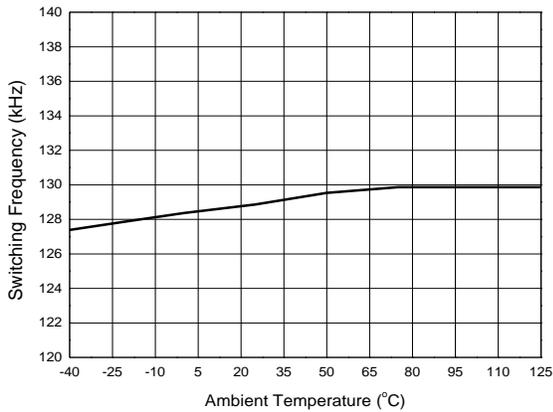
**I<sub>CC\_ST</sub> Startup Current vs. Ambient Temperature**



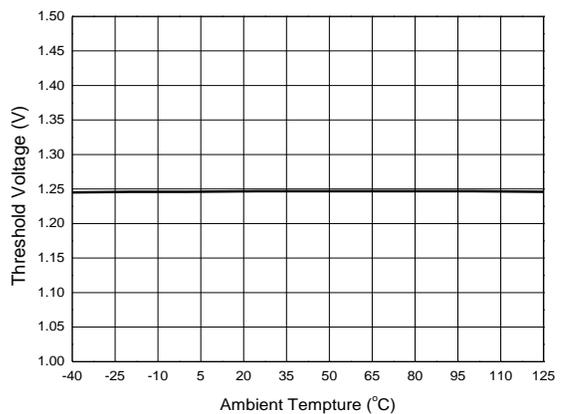
**I<sub>CC\_OP</sub> Operating Current vs. Ambient Temperature**



**Maximum Switching Frequency in Peak Load vs. Ambient Temperature**



**Threshold Voltage of Secondary Rectifier Short Protection vs. Ambient Temperature**



## Operation Description

The AP3129 implements a multi-mode flyback converter utilizing peak current control the switch off event. It operates in continuous condition mode (CCM) and valley-on switching to provide high-efficiency solution. The IC is an ideal candidate where low parts count and cost effectiveness are the key parameters in AC-DC adapters.

### Startup Timing

VCC capacitor charging current comes from divided resistor for X-CAP discharging in AC input terminal. When the VCC is rising up to the startup voltage ( $V_{CC\_ON}$ ), the current source turns off. And the AP3129 will output 4 switching pulses to detect the  $I_{DEMAG}$  current flowing through the DEMAG pin pullup resistor. Thus, the AC line voltage can be detected. If the input voltage is lower than the brown-in voltage, the IC will enter into restart status. Once the input voltage is higher than the brown-in voltage, the AP3129 will start working, the output voltage will ramp up, and the auxiliary winding voltage is going up accordingly. The VCC voltage begins going down from  $V_{CC\_ON}$  till VCC capacitor charging is taken over by the auxiliary winding voltage.



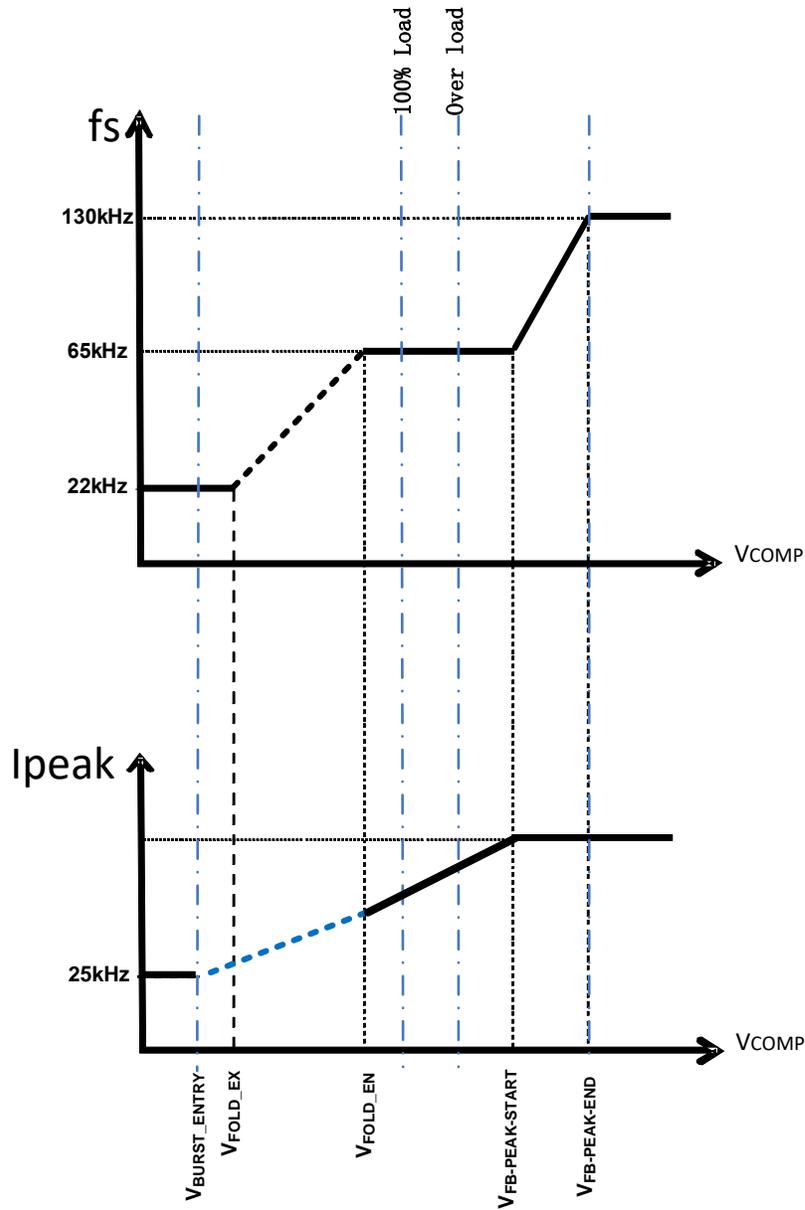
**Figure 1. Startup Timing**

### Frequency Control Strategy

As shown in Figure 2, the AP3129 changes operating modes according to different load conditions. When the device operates in CCM mode in heavy load in low line voltage, it is advantageous to achieve high power conversion efficiency, and is possible to implement a small-sized adapter with a small transformer. There are some special applications (smart speakers, printers, etc.) where the output load heavily changes from a normal to a peak value. At this time, to avoid growing the transformer size, an optional technique consists in clamping the peak current up to a maximum value, and authorizes frequency increase to a certain point (130kHz) to let the converter deliver more power to output. This power excursion can only be temporary and its duration is set by the internal overload timer

When the loading goes low, the system enters into QR mode or green mode with valley-on switching, and it can significantly reduce switching loss, especially in high line. Thus, high power conversion efficiency can be achieved. In order to avoid an excessive switching loss at very high switching frequency operations, there is a fixed 80kHz frequency limitation. As the load decreases, the internal oscillators reduce its switching frequency according to the feedback level. Once the COMP pin voltage is lower than  $V_{BURST\_ENTRY}$ , the controller enters burst mode, and the peak current freezes to a fixed value. Operating in this mode ensures high efficiency at low power and excellent no-load power performance. A minimum clamp frequency will prevent the switching frequency from dropping below 22kHz to eliminate the risk of audible noise.

**Operation Description** (continued)

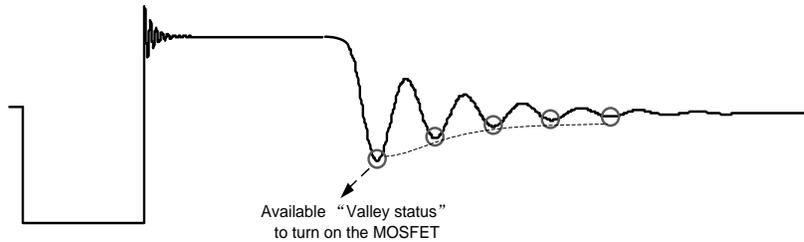


**Figure 2. Operation Frequency Curve**

**Valley-On Switching**

Valley-on switching is regarded as a soft switching technology which always turns on the primary MOSFET at the valley status of the Drain-to-Source voltage ( $V_{DS}$ ). Compared to traditional hard switching, it can reduce the switching power loss of MOSFET and achieve good EMI behavior without additional BOM cost.

**Operation Description** (continued)

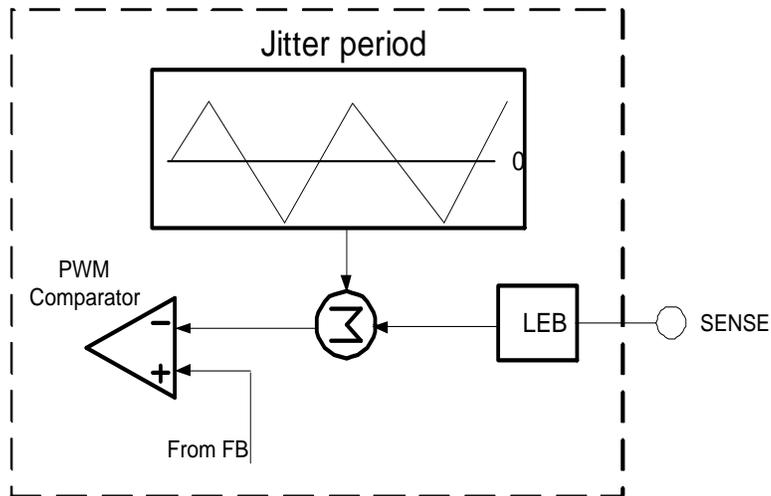


**Figure 3. Valley Detection**

Figure 3 shows the primary MOSFET  $V_{DS}$  waveform. When the secondary-side current drops to zero, the primary inductance  $L_M$  and the effective MOSFET output capacitor  $C_{oss}$  begins to resonant. The resonant frequency is approximately  $1/2\pi\sqrt{L_M * C_{oss}}$ . The IC controller takes advantage of the drain voltage ringing and turns on the power switch at the drain ringing voltage valley to reduce switching loss and EMI. The valley is detected by the DEMAG pin through a pair of voltage dividers. At the primary MOSFET turning-off time once the voltage on the DEMAG pin is detected below 35mV, one “valley status” is counted. According to the frequency control strategy of the AP3129, one proper “valley status” will be selected to turn on the MOSFET. To prevent a false-trigger of the  $V_{DS}$  ring caused by a leakage inductance, the valley detection function is blanked within the  $t_{BLK\_DEMAG}$  when the primary MOSFET turns off. When the COMP voltage decreases, the current “valley-on status” is forced to shift to another available “valley-on status”. The maximum valley number for turn-on reaches to the tenth. When the valley quantities exceed tenth valleys, the system will operate in hard switching conditions.

**Frequency Jittering**

The AP3129 integrates an active frequency-dithering function to improve the EMI performance. As shown in Figure 4, an internal low frequency modulation signal varies the pace at which the oscillator frequency is modulated, and produces a periodical excursion. This helps spread out energy in conducted noise analysis. To improve the EMI performance during low power and middle power level, the jittering circuit persists in working in frequency foldback mode because of an innovative implementation of the AP3129.



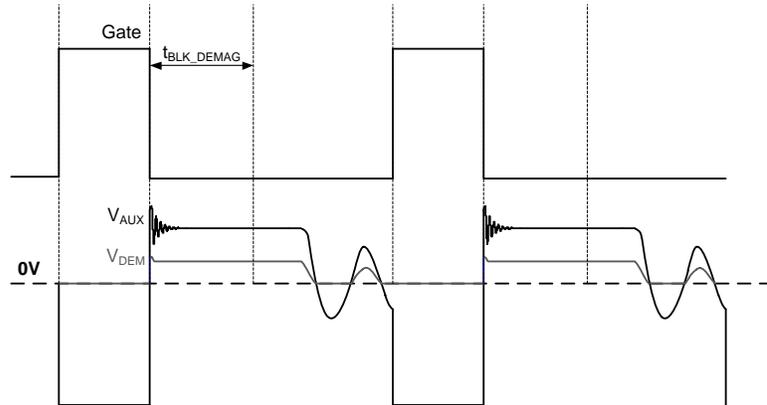
**Figure 4. Frequency Jittering**

**Operation Description** (continued)

**VOUT OVP & UVP**

The AP3129 provides output OVP and UVP protection function. The auxiliary winding voltage during secondary rectifier conducting period reflects the output voltage. A divided voltage network is connected to the auxiliary winding and DEMAG pin. The DEMAG pin will detect the equivalent output voltage with a delay of  $t_{BLK\_DEMAG}$  from the falling edge of the GATE driver signal, as shown in Figure 5. The detected voltage will be compared to the inner SOVP and SUVP threshold voltage. If the SOVP or SUVP threshold is reached continuously by 6 switching cycles, the SOVP or SUVP protection will be triggered, the AP3129 will shut down switching pulses, and the system will restart when the  $V_{CC}$  voltage falls below the UVLO voltage.

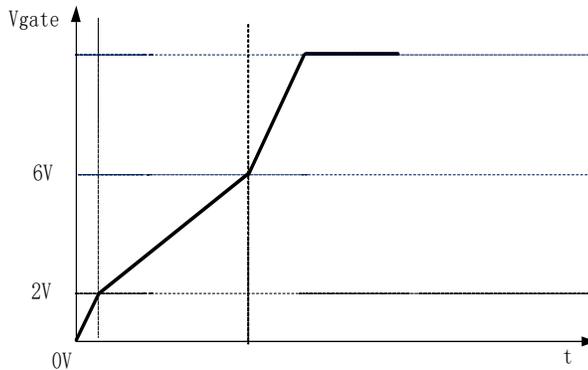
To prevent a false-trigger of the SUVP during startup process, the SUVP protection function will be ignored for a blank time of  $t_{D\_UVP}$ .



**Figure 5. SOVP and SUVP**

**Soft Driver**

The AP3129 gate sinking current is higher than 600mA, and the drive control includes three steps (see Figure 6). The first step is from 0V to 2V driving voltage, and the second step is from 2V to 6V within a period of 250ns. The third step is from 6V up to the gate clamp voltage. For the first-step and third-step, the gate voltage will be charged rapidly in a remarkable short time, which makes the MOSFET switching loss drop to a relatively low level. And the second step is expected to hold 250ns to get a relative long Miller time for improving EMI performance. This driver solution is a good balance of EMI performance and efficiency.



**Figure 6. Soft Driver**

**Operation Description** (continued)

**Overload Protection (OCP1/OCP2)**

An integrated overload protection circuit provides a relatively constant power limit across over the whole line voltage. As shown in Figure 5, during the turn-on time, the  $V_{aux}$  drops to  $-N \cdot V_{IN}$ ,  $N$  being the turns ratio between the primary winding and the auxiliary winding and  $V_{IN}$  being the input bulk voltage. The negative plateau voltage of the DEMAG pin has a proportion amplitude of the input voltage, so an integrated sensing circuit in AP3129 measures the input bulk voltage via the DEMAG pin. As the output power of system reaches a defined set limit, the corresponding  $V_{SENSE}$  should touch an internal overpower reference voltage ( $V_{TH\_OCP1}$ ). If the overload situation lasts continuously for 60ms, an overload protection circuit would be triggered and the system would enter into restart mode.

If the output power and the feedback voltage continue to rise up, AP3129 would authorize a transient peak load with a higher  $V_{SENSE}$  threshold ( $V_{TH\_OCP2}$ ) and a higher switching frequency (130kHz) for a period of 60ms. When the feedback voltage reaches up to the open-loop level ( $V_{COMP\_OPEN}$ ), which lasts more than 15ms, the device will enter an auto-recovery hiccup status. If the fault situation lasts less than set-time 15ms, the feedback will returns to its regulation level and resets the timer of peak-load-control circuit.

**Line Compensation**

A higher OCP current often occurs along with turn-off delay time of the MOSFET at high line voltage. To obtain a constant OCP current value with universal input voltage, an effective line compensation circuitry must be applied to the AP3129. The function block is illustrated in Figure 7. The current  $I_{DEMAG}$ , which reflects line voltage, is scaled down and inverted to  $I_{L\_OPP}$  within the AP3129, this  $I_{L\_OPP}$  flows through the inner compensation resistor  $R_{OPP}$  and an external filtering resistor  $R_F$ . The final line compensation voltage is formed as:

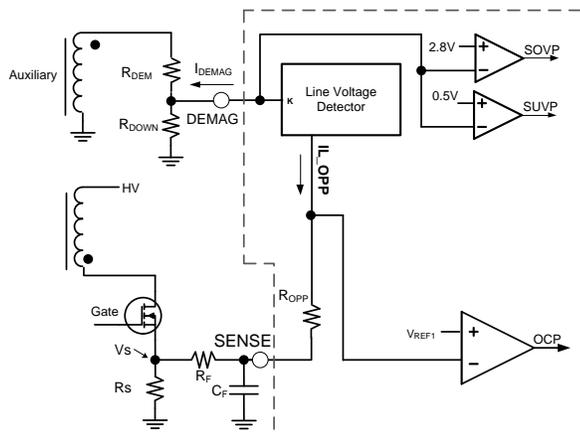
$$V_s = V_{REF1} - I_{L\_OPP} * (R_{OPP} + R_F), \quad (I_{L\_OPP} = \frac{V_{indc} \cdot N_{aux}}{N_p \cdot R_{dem} \cdot K})$$

Where,  $V_s$  is the sense voltage of  $R_s$ , "K" is the current proportional coefficient, and  $R_{OPP}$  is decided by line voltage.

$R_{DEM}$  value is relevant with brown-in/out voltage, which is fixed (105kΩ recommended) to specific turn-ratio transformer system.

In a real system, the line compensation can be checked according to OCP1 under 115Vac line voltage condition. The corresponding parameters are set by  $V_{REF1} = 0.525V$ ,  $K = 24$ ,  $R_{OPP} = 40k\Omega$ ,  $R_F = 1k\Omega$

As is indicated from the above formula, when the  $V_{REF1}$  and  $R_{DEM}$  values are fixed, changing  $R_F$  is an alternative way to adjust the line compensation, especially at high line voltage. Once the  $R_F$  value is confirmed, it also needs to adjust the  $C_F$  simultaneously to offer enough RC time to filter the spike on the SENSE pin.



**Figure 7. Line Compensation**

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## Operation Description (continued)

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### Slope Compensation

The primary current is followed by the COMP voltage. When the primary peak current reaches the reference determined by  $V_{COMP}$ , the gate driver will be turned off. In order to avoid sub-harmonic oscillation, slope compensation is essential for peak-current mode when the duty cycle is above 50%. Even though the duty is below 50%, it is desirable to add a slope compensation to decrease the influence of external noise. The AP3129 offers an internal slope compensation signal (typically 33mV/ $\mu$ s) that can easily be summed up to the sensed current. Sub harmonic oscillations can thus be compensated. This allows the AP3129 to work with a wide input voltage.

### Overtemperature Protection

The AP3129 integrates an internal temperature protection to prevent permanent damage by overtemperature. If the junction temperature exceeds the temperature protection threshold of +130°C, the IC will trigger the internal OTP and stop switching. Meanwhile, if the VCC drops to VCC UVLO threshold  $V_{CC\_UVLO}$ , the controller enters restart mode. A built-in hysteresis ensures that if the internal temperature drops to +115°C, the IC will recover operation.

### Others System Protection

#### $V_{BULK\_OVP}$ , FOC, SSCP, VCC OVP, SCP

The AP3129 provides versatile protections to ensure the reliability of the power system.  $V_{BULK\_OVP}$  represents line voltage overvoltage protection. If the detected AC line voltage is higher than  $V_{BULK\_OVP}$  and sustains for 2.8s, the  $V_{BULK\_OVP}$  protection will be triggered.

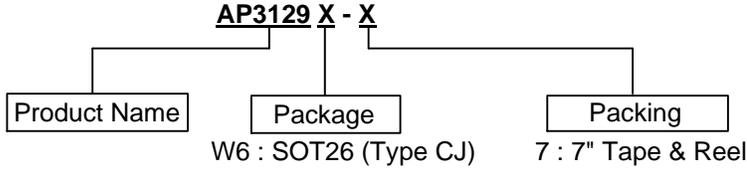
FOCP (Fast overcurrent protection) is an ultra-fast short-current protection which is helpful to prevent catastrophic damage of the system when the secondary rectifier is shorted. The primary peak current will be monitored by the SENSE pin through a primary sense resistor. Whenever the sampled voltage reaches the threshold of  $V_{TH-FOCP}$  for 6 switching cycles continuously, the FOC will be activated to shut down the switching pulse.

SSCP (Sensor short-circuit protection) might be triggered when the SENSE pin is shorted to the ground. The SSCP module senses the voltage across the primary sense resistor with a several microsecond delay time after the rising edge of the primary GATE signal. This sensed signal is compared with  $V_{TH-SSCP}$ . If it is lower than  $V_{TH-SSCP}$  for 6 switching cycles, the SSCP will be triggered and the drive signal will be disabled. To prevent a false-trigger, the SSCP is valid only within the initial 25ms after startup.

VCC overvoltage protection is used to prevent IC damage from overvoltage stress. All these protections described will restart the system when the VCC voltage falls below UVLO.

If the power supply experiences a severe overloading situation or the output of the system is under a short-circuit test, the driving pulses will stop and VCC will fall down as the auxiliary pulses are missing. When VCC drops below  $V_{CC\_UVLO}$ , the controller consumption is down to a few  $\mu$ A and VCC slowly rises up again via resistive starting network. When VCC reaches up to  $V_{CC\_ON}$ , the controller purposely ignores the restart cycle and waits for another VCC cycle. AP3129 naturally reaches a remarkable low input power by lowering the duty ratio in fault condition.

**Ordering Information**

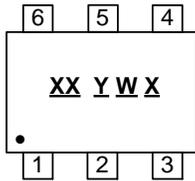


Part Number	Package	Identification Code	Packing	
			Qty.	Carrier
AP3129W6-7	SOT26 (Type CJ)	B4	3000	Tape & Reel

**Marking Information**

Package Type: SOT26 (Type CJ)

**(Top View)**

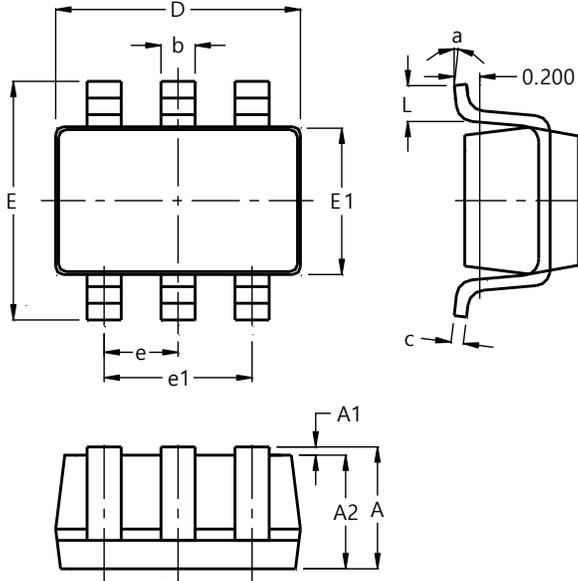


- XX : Identification Code
- Y : Year 0 to 9 (ex: 3 = 2023)
- W : Week : A to Z : week 1 to 26;  
a to z : week 27 to 52; z represents week 52 and 53
- X : Internal Code

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26 (Type CJ)

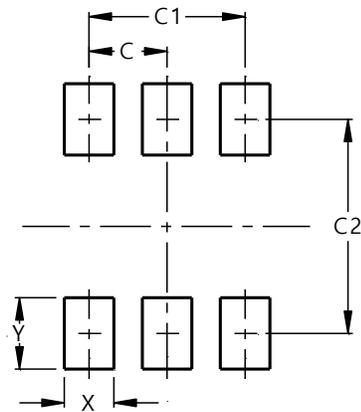


SOT26 (Type CJ)			
Dim	Min	Max	Typ
A	1.050	1.250	--
A1	0.00	0.10	--
A2	1.050	1.150	--
b	0.300	0.500	--
c	0.100	0.200	--
D	2.820	3.020	--
E	2.650	2.950	--
E1	1.500	1.700	--
e	0.950BSC		
e1	1.800	2.000	--
L	0.300	0.600	--
a	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT26 (Type CJ)



Dimensions	Value (in mm)
C	0.95
C1	1.90
C2	2.40
X	0.60
Y	1.00

**Mechanical Data**

- Moisture Sensitivity: Level 3 per JESD22-A113
- Terminals: Finish – Matte Tin Plated Leads, Solderable per JESD22-B102 ③
- Weight: 0.016/0.017 grams (Approximate)

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